

Half Bridge SiC MOSFET Module

High performance:

- Sintered die – DBC interface
- No wirebonds for power transfer
- Sintered clips

NTC embedded on the die

Advantages of sintering over soldering:

- Voidless interface (see X-Ray)
- Can handle 5x more temperature cycles
- Lower thermal resistance

Current rating: 30A continuous in an actual automotive application

Same enclosure can fit double the current rating

Scalable concept up to far greater currents

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X-Ray Half Bridge SiC MOSFET Module

